

**IN THE CLAIMS:**

Please cancel claims 1, 3 and 5-8.

Claims 2, 4, and 9 wer previously cancelled in Applicant's Amendment dated June 23, 2003. Applicant appreciates the allowance of claim 10 which is also attached hereinunder.

1. (Cancelled).
2. (Cancelled).
3. (Cancelled).
4. (Cancelled).
5. (Cancelled).
6. (Cancelled).
7. (Cancelled).
8. (Cancelled).
9. (Cancelled).

10. (Original) An apparatus for testing internal components of an integrated circuit package device under test to determine normal operation or problem areas in the components, said apparatus comprising:

(a) test socket means for connecting the device under test with a digital multimeter in order to measure the power bus-to ground resistance of the internal components;

(b) temperature transfer block means connected to a temperature meter for placement adjacent said device under test in order to increase the ambient heat or decrease the ambient heat to said device under test;

(c) a Peltier-thermal electric module adjunct said transfer block means and connected to a programmable power supply for controlling the addition of heat to or reduction of heat from said temperature transfer block;

(d) heat sink and fan means placed adjunct to said Peltier thermal electric module and connected to a controlled fan power supply;

(e) computer means having a control program for connection and management of said controlled fan power supply, said programmable power supply and for sensing operations of said temperature meter and said digital multimeter to controllably enable the sequencing of an up-ramp temperature and a down ramp temperature adjacent said device under test, while concurrently reading-out and plotting the power bus-to ground voltage during the up-cycle and down-cycle of the temperature applied to said device under test.